Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A method for manufacturing circuit devices, the method comprising:

forming conductive patterns on a planar body, the conductive patterns forming mounting portions ~~including mounting areas~~ for [[of a]] circuit ~~element~~ elements;

disposing [[the]] a circuit element on at least one of the mounting portions ~~the conductive pattern~~;

performing resin sealing by bringing a backface of the planar body into contact with a lower mold having air vents ~~into contact with a backface of the planar body~~ and by sealing a surface of the planar body with an insulating resin so that the circuit element is covered therewith; and

separating each mounting portion.

2. (Currently Amended) The method for manufacturing circuit devices as set forth in Claim 1 further comprising forming a block that includes ~~, wherein blocks are formed by~~ a plurality of the mounting portions arranged in a matrix form, ~~and~~ wherein performing resin sealing comprises covering a plurality of circuit elements, each circuit element being coupled to one of the mounting portions. ~~is performed by each cavity in each block~~.

3. (Currently Amended) The method for manufacturing circuit devices as set forth in Claim 1, wherein the planar body is a conductive foil, the conductive foil having a surface provided with conductive patterns formed in a convex shape ~~shaped~~ by separation grooves.[[,]]

4. (Original) The method for manufacturing circuit devices as set forth in Claim 1, wherein the planar body is an insulating sheet having multi-layered conductive patterns laminated via an insulating layer.

5. (Original) The method for manufacturing circuit devices as set forth in Claim 1, wherein the air vents are disposed in parallel.

6. (Currently Amended) The method for manufacturing circuit devices as set forth in Claim 5, wherein [[the]] an air vent provided at a central part is formed to be larger than [the] an air vent provided at a peripheral part.

7. (Currently Amended) The method for manufacturing circuit devices as set forth in Claim 1, wherein a remaining part of the ~~planner~~ planar body around the block is sandwiched by a mold.

8. (Original) The method for manufacturing circuit devices as set forth in Claim 1, wherein the circuit element has either one of or both of a semiconductor bare chip and a chip circuit component fixed thereto.

9. (Currently Amended) The method for manufacturing circuit devices as set forth in Claim 1, wherein a plurality of blocks are aligned, in each block the conductive patterns ~~forming~~ form a plurality of mounting portions [[are]] arranged in a matrix form on the ~~planner~~ planar body.

10. (Original) The method for manufacturing circuit devices as set forth in Claim 9, wherein the insulating resin is formed by simultaneously subjecting all of the blocks of the conductive foil to transfer molding.

11. (Original) The method for manufacturing circuit devices as set forth in Claim 1, wherein the air vent strides over a peripheral part of the cavity and is extended from inside the cavity to an outer part of the cavity.

12. (New) The method for manufacturing circuit devices as set forth in Claim 1 wherein bringing the backface of the planar body into contact with the lower mold having air vents comprises bringing the backface of the planar body into contact with at least one of the air vents.

13. (New) The method for manufacturing circuit devices as set forth in Claim 12 wherein bringing the backface of the planar body into contact with at least one of the air vents comprises enabling the release of air through the air vent from between the planar body and the lower mold.

14. (New) The method for manufacturing circuit devices as set forth in Claim 12 wherein bringing the backface of the planar body into contact with the lower mold having air vents comprises sealing at least one of the air vents with the backface of the planar body.